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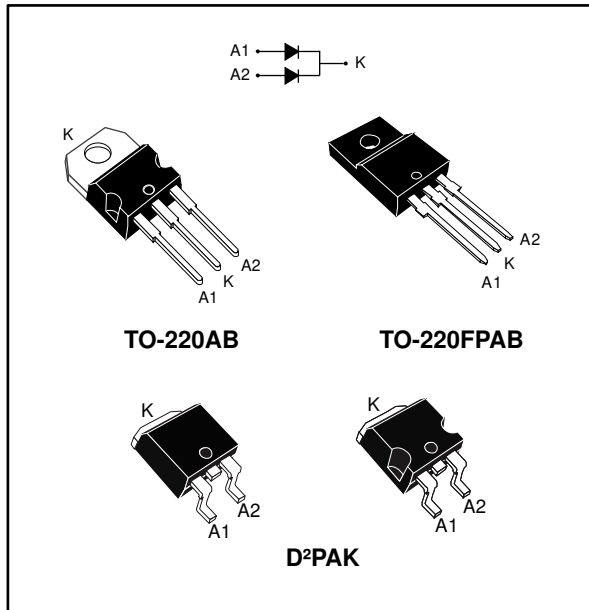
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High voltage power Schottky rectifier

Datasheet - production data



Description

Dual center tap Schottky rectifier diode suited for high frequency switched mode power supplies.

Table 1: Device summary

Symbol	Value
$I_{F(AV)}$	2 x 10 A
V_{RRM}	170 V
T_j (max.)	175 °C
V_F (typ.)	0.69 V

Features

- High reverse voltage
- High junction temperature capability
- Avalanche specification with derating curves
- Insulated package TO-220FPAB
 - Insulating voltage: 2000 V_{RMS} sine
- ECOPACK[®]2 compliant component for D²PAK on demand

Benefits

- Can challenge bipolar ultrafast diodes with better dynamic characteristics

1 Characteristics

Table 2: Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit	
V _{RRM}	Repetitive peak reverse voltage			170	V	
I _{F(RMS)}	Forward rms current			30	A	
I _{F(AV)}	Average forward current δ = 0.5, square wave	TO-220AB / D ² PAK	T _C = 155 °C	Per diode	10	A
			T _C = 150 °C	Total	20	
		TO-220FPAB	T _C = 135 °C	Per diode	10	
			T _C = 115 °C	Total	20	
I _{FSM}	Surge non repetitive forward current		t _p = 10 ms sinusoidal	180	A	
P _{ARM}	Repetitive peak avalanche power		t _p = 10 μs, T _j = 125 °C	480	W	
T _{stg}	Storage temperature range			-65 to +175	°C	
T _j	Maximum operating junction temperature ⁽¹⁾			175		

Notes:

⁽¹⁾(dP_{tot}/dT_j) < (1/R_{th(j-a)}) condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal parameters

Symbol	Parameter		Max. value	Unit	
R _{th(j-c)}	Junction to case	TO-220AB / D ² PAK	Per diode	2.2	°C/W
			Total	1.3	
		TO-220FPAB	Per diode	4.5	
			Total	3.5	
R _{th(c)}	Coupling	TO-220AB / D ² PAK	0.3		
		TO-220FPAB	2.5		

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j (\text{diode1}) = P_{(\text{diode1})} \times R_{th(j-c)} (\text{per diode}) + P_{(\text{diode2})} \times R_{th(c)}$$

Table 4: Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		15	μA
		$T_j = 125\text{ °C}$		-		15	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 10\text{ A}$	-		0.90	V
		$T_j = 125\text{ °C}$		-	0.69	0.75	
		$T_j = 25\text{ °C}$	$I_F = 20\text{ A}$	-		0.99	
		$T_j = 125\text{ °C}$		-	0.79	0.86	

Notes:

(1) Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

(2) Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 0.64 \times I_{F(AV)} + 0.011 \times I_{F(RMS)}^2$$

1.1 Characteristics (curves)

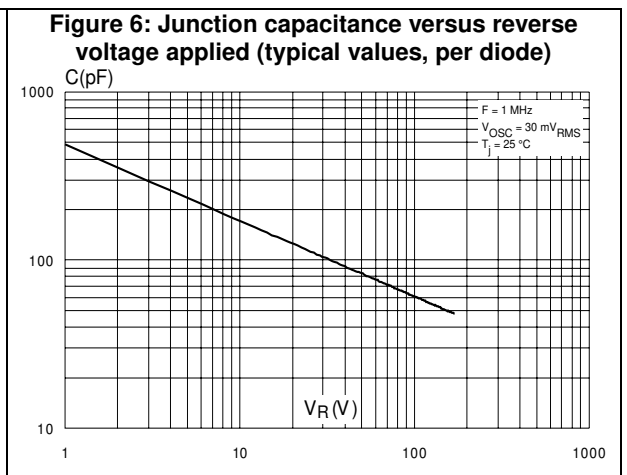
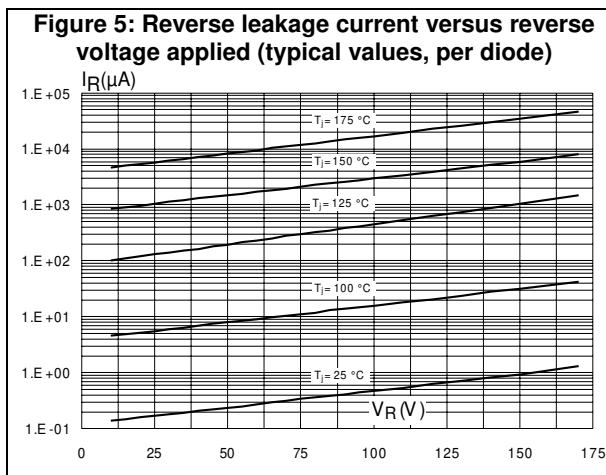
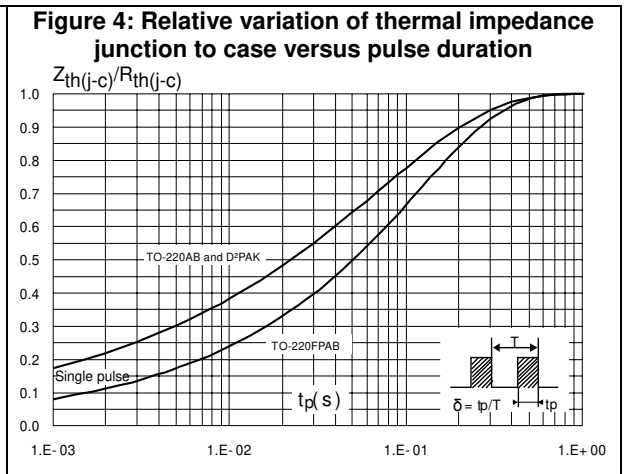
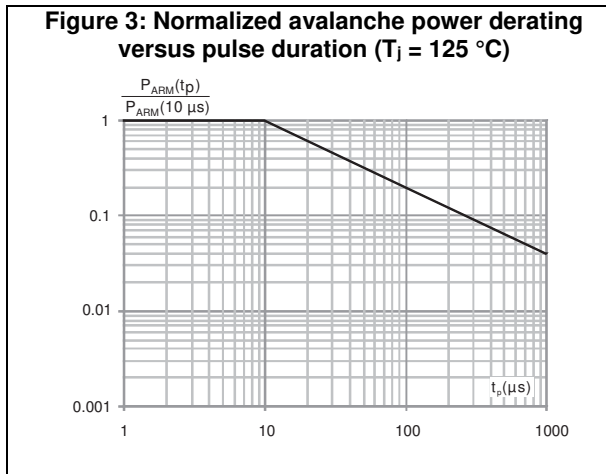
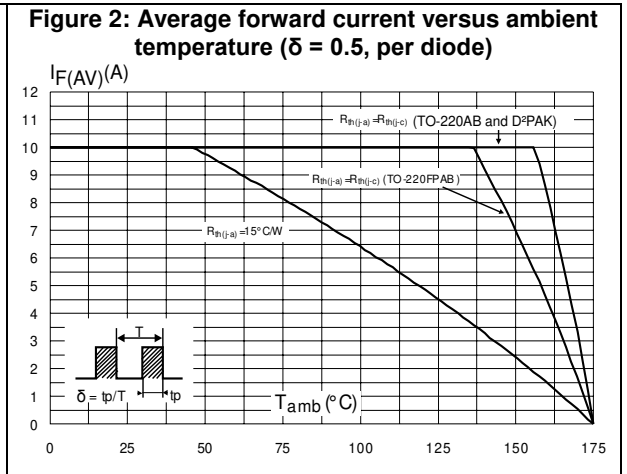
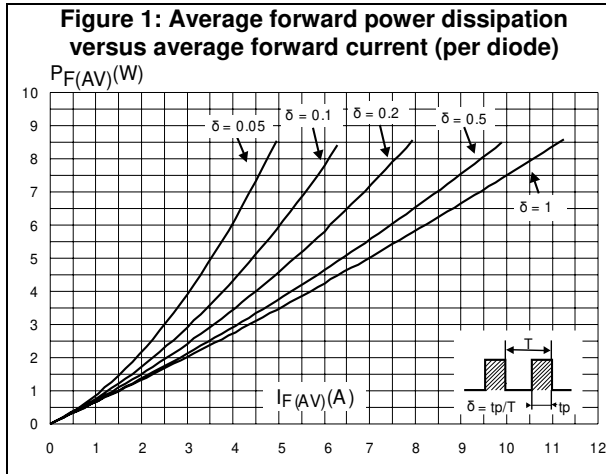


Figure 7: Forward voltage drop versus forward current (per diode)

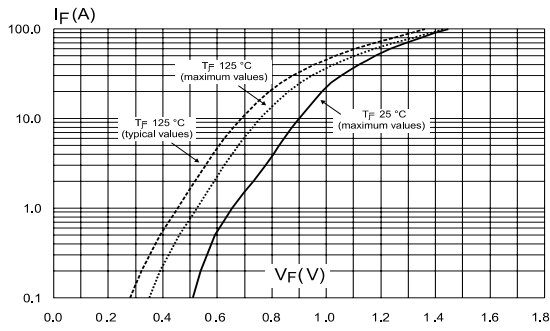
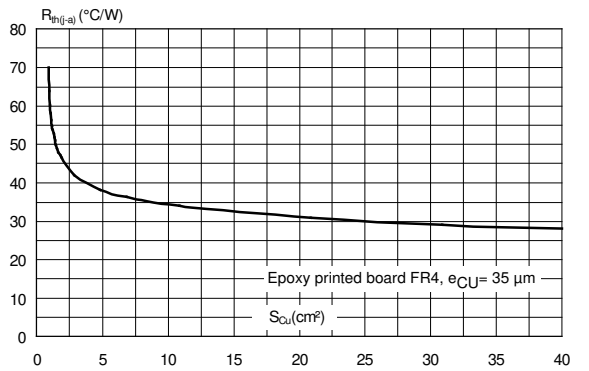


Figure 8: Thermal resistance junction to ambient versus copper surface under tab for D²PAK



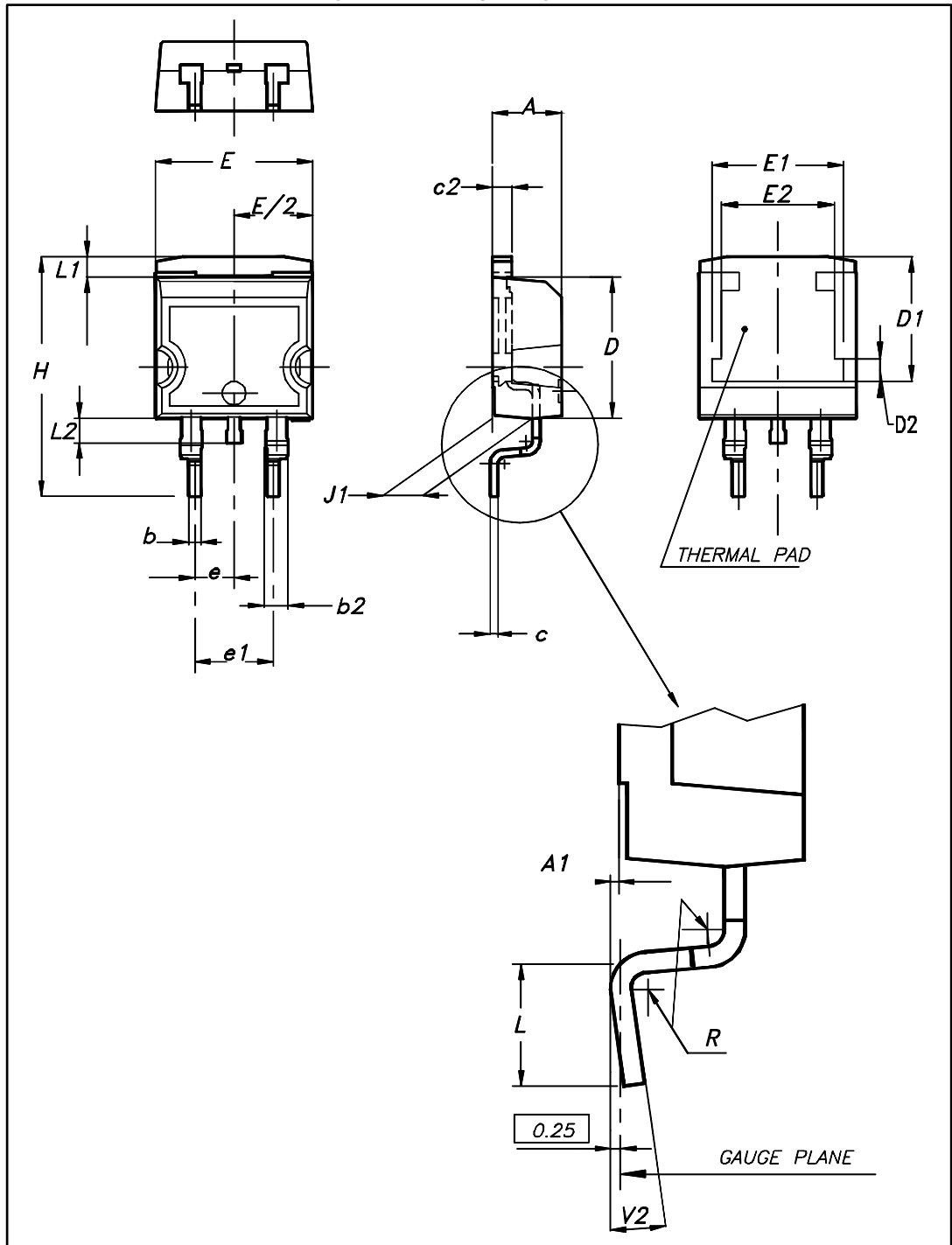
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94, V0
- Recommended torque value: 0.55 N·m (for TO-220AB and TO-220FPAB)
- Maximum torque value: 0.7 N·m (for TO-220AB and TO-220FPAB)

2.1 D²PAK package information

Figure 9: D²PAK package outline

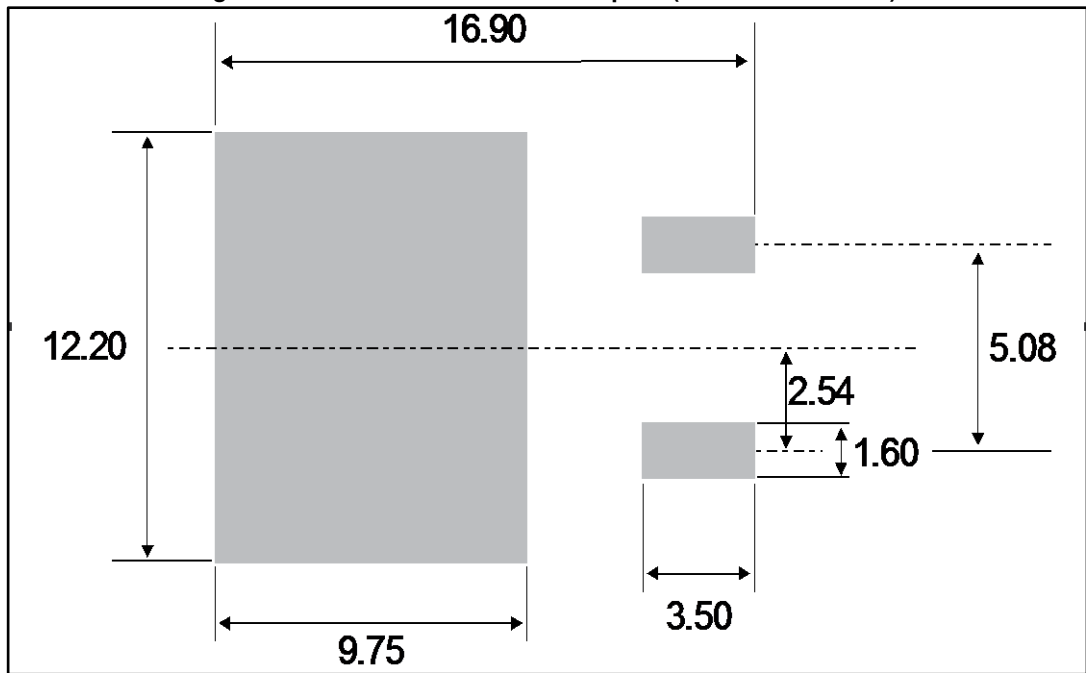


This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 5: D²PAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.36	4.60	0.172	0.181
A1	0.00	0.25	0.000	0.010
b	0.70	0.93	0.028	0.037
b2	1.14	1.70	0.045	0.067
c	0.38	0.69	0.015	0.027
c2	1.19	1.36	0.047	0.053
D	8.60	9.35	0.339	0.368
D1	6.90	8.00	0.272	0.311
D2	1.10	1.50	0.043	0.060
E	10.00	10.55	0.394	0.415
E1	8.10	8.90	0.319	0.346
E2	6.85	7.25	0.266	0.282
e	2.54 typ.		0.100	
e1	4.88	5.28	0.190	0.205
H	15.00	15.85	0.591	0.624
J1	2.49	2.90	0.097	0.112
L	1.90	2.79	0.075	0.110
L1	1.27	1.65	0.049	0.065
L2	1.30	1.78	0.050	0.070
R	0.4 typ.		0.015	
V2	0°	8°	0°	8°

Figure 10: D²PAK recommended footprint (dimensions in mm)



2.2 TO-220FPAB package information

Figure 11: TO-220FPAB package outline

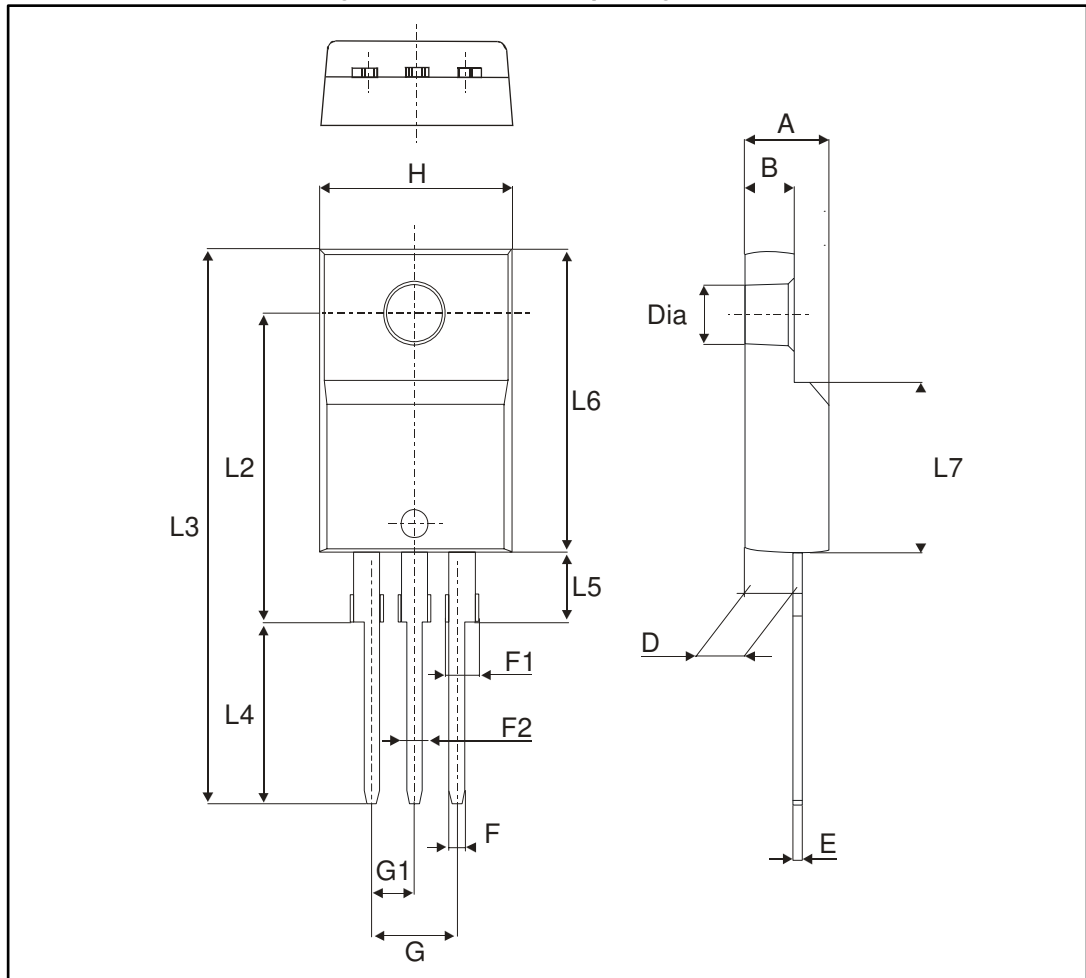


Table 6: TO-220FPAB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.50	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1.0	0.03	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.40	2.70	0.094	0.106
H	10.00	10.40	0.393	0.409
L2	16.00 typ.		0.63 typ.	
L3	28.60	30.60	1.126	1.205
L4	9.80	10.6	0.386	0.417
L5	2.90	3.60	0.114	0.142
L6	15.90	16.40	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia	3.0	3.20	0.118	0.126

2.3 TO-220AB package information

Figure 12: TO-220AB package outline

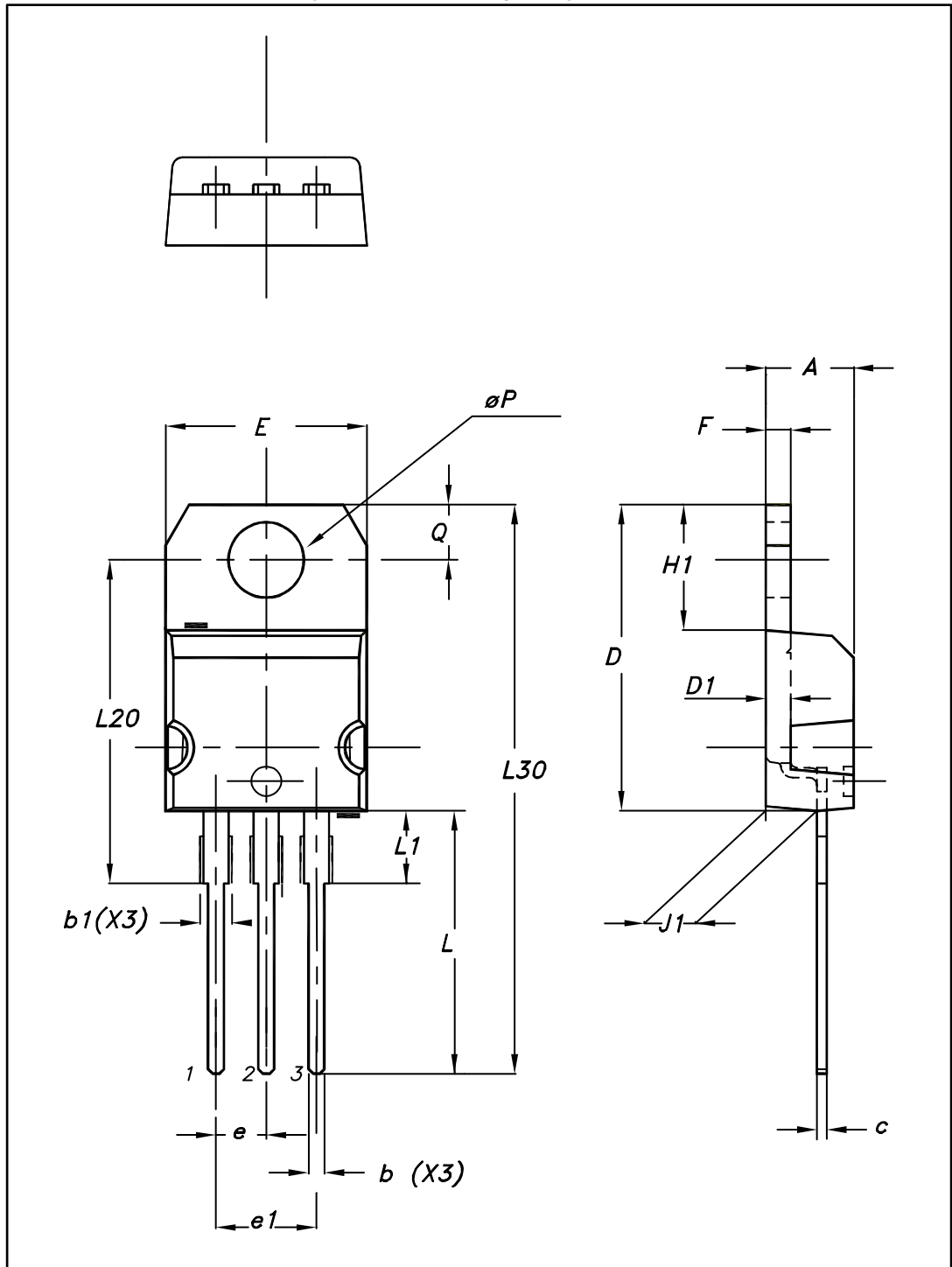


Table 7: TO-220AB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.70	0.045	0.067
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27 typ.		0.050 typ.	
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138 typ.	
θP	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

3 Ordering information

Table 8: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS20170CT	STPS20170CT	TO-220AB	1.95 g	50	Tube
STPS20170CFP	STPS20170CFP	TO-220FPAB	1.7 g	50	Tube
STPS20170CG-TR	STPS20170CG	D ² PAK	1.38 g	1000	Tape and reel

4 Revision history

Table 9: Document revision history

Date	Revision	Changes
Mar-2004	1	First issue.
28-Jul-2005	2	TO-220FPAB, I ² PAK and D ² PAK packages added.
14-Oct-2016	3	Removed I ² PAK package. Updated features and packages silhouettes in cover page. Updated Section 5: "Characteristics" , Section 5.1: "Characteristics (curves)" , Table 8: "Ordering information" and Section 6.2: "D²PAK package information" .

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